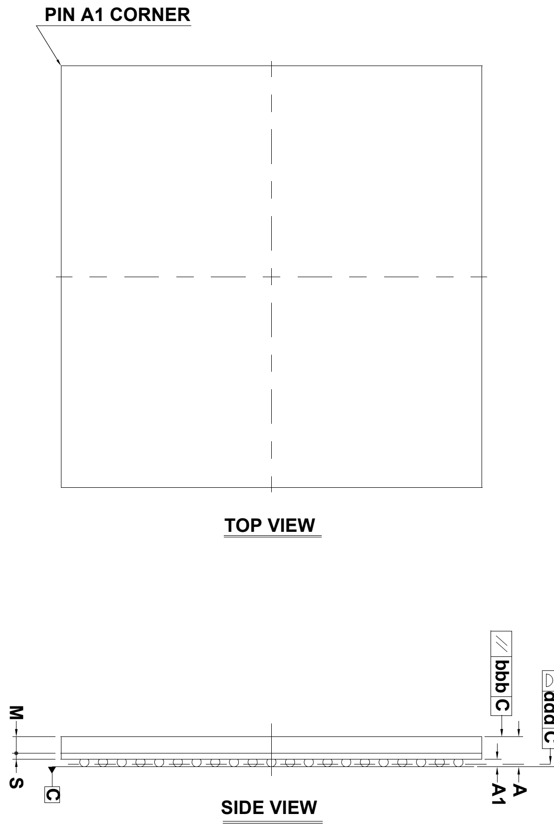
Package Outline Drawing

V409.18x18

409 LOW PROFILE FINE PITCH PLASTIC BALL GRID ARRAY PACKAGE (LFBGA)

Rev 0, 3/12



		SYMBOL	COMMON DIMENSIONS
Package			LFBGA
Body Size	X	E	18.00
	Y	D	18.00
Ball Pitch			0.800
Total Thickness		A	1.400 MAX
Mold Thickness		M	0.700 Ref.
Substrate Thickness		S	0.260 Ref.
Ball Diameter			0.400
Stand Off		A1	0.270 ~ 0.370
Ball Width		b	0.380 ~ 0.480
Package Edge Tolerance		aaa	0.150
Mold Flatness		bbb	0.200
Coplanarity		ddd	0.120
Ball Offset (Package)		eee	0.150
Ball Offset (Ball)		fff	0.080
Ball Count		n	409
Edge Ball Center to Center	X	E1	16.00
	Y	D1	16.00